

FIG.1A

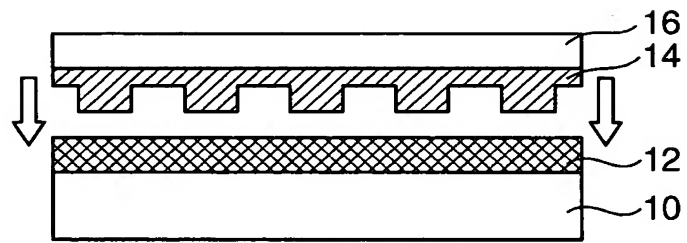


FIG.1B

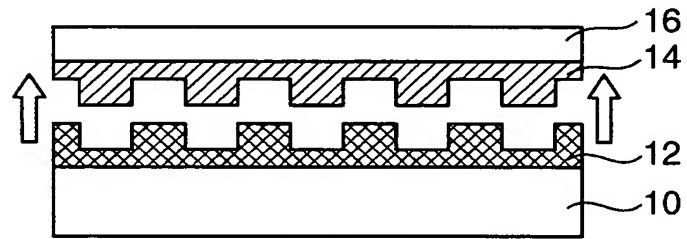


FIG.1C

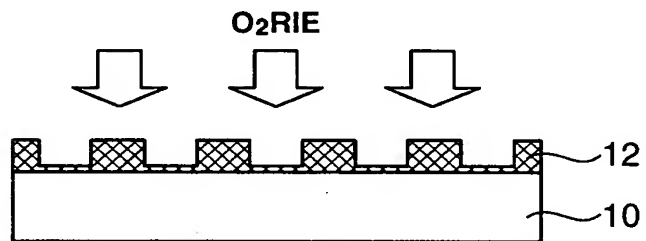


FIG.2A
INITIAL

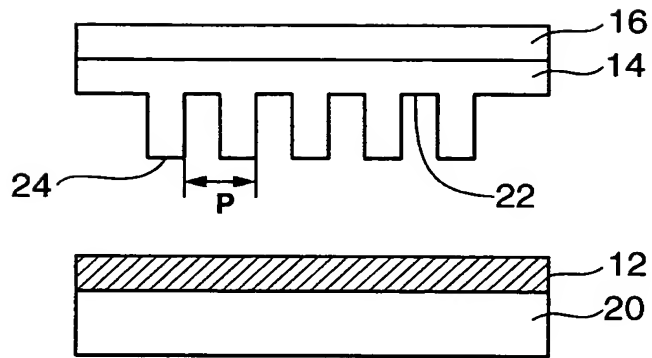


FIG.2B
TRANSFER

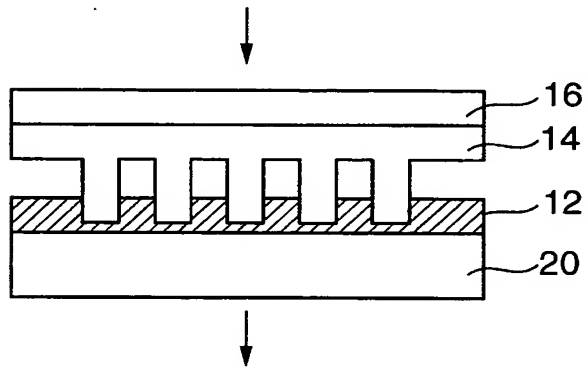


FIG.2C
SEPARATION

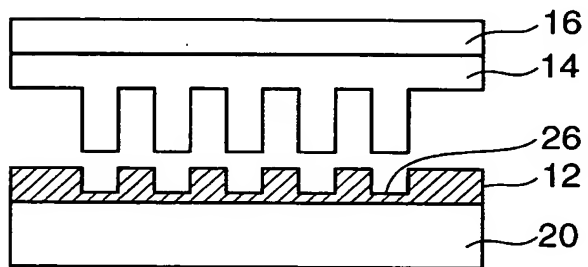


FIG.2D
RIE

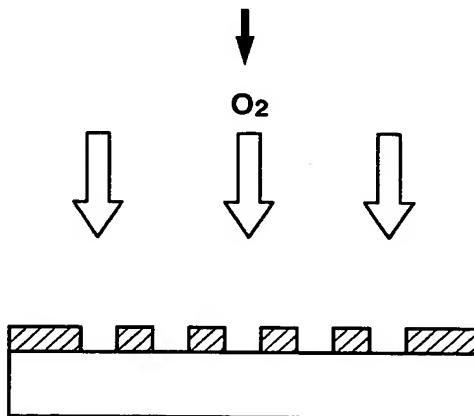


FIG.3A

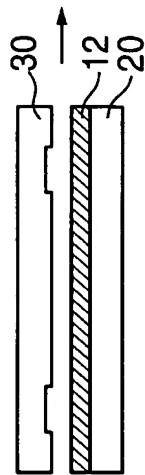


FIG.3B

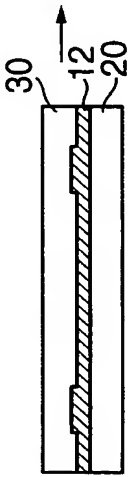


FIG.3C

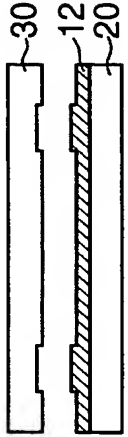


FIG.3D

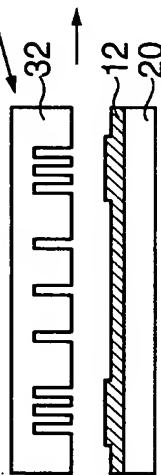


FIG.3E

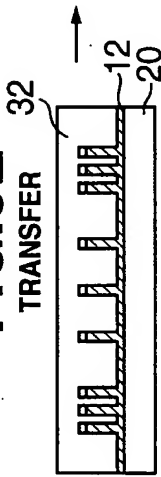


FIG.3F

SEPARATION

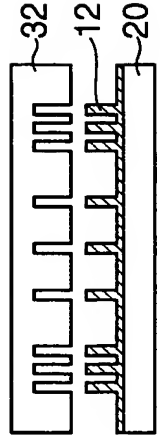


FIG.3G

O₂ RIE

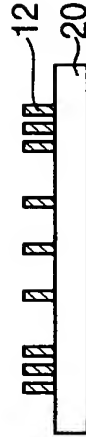


FIG.4

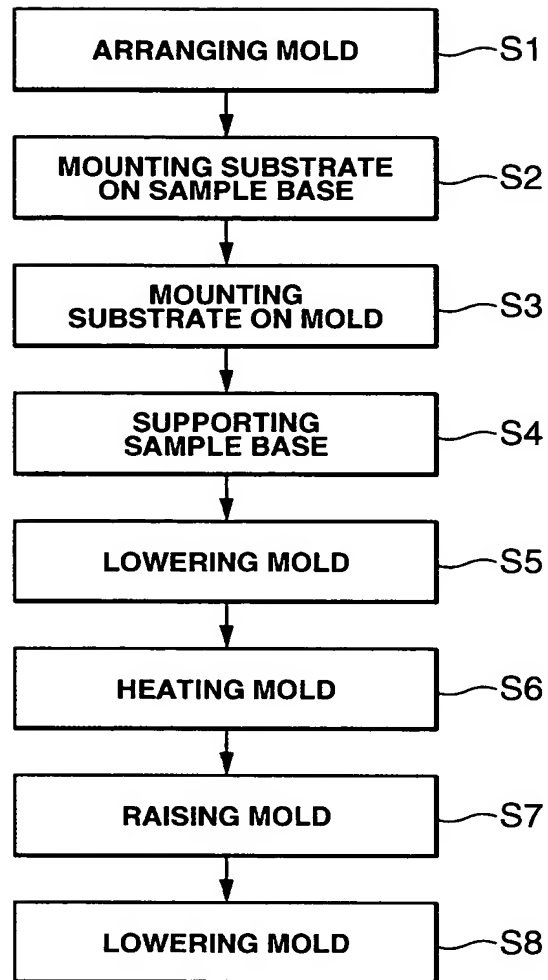


FIG.5A

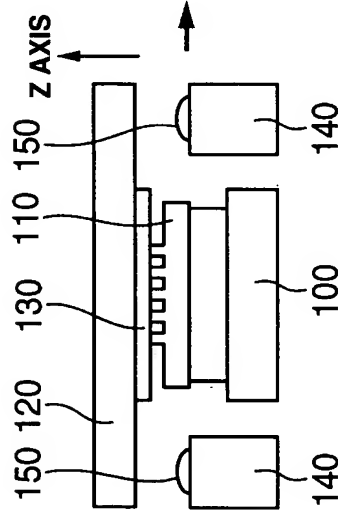


FIG.5B

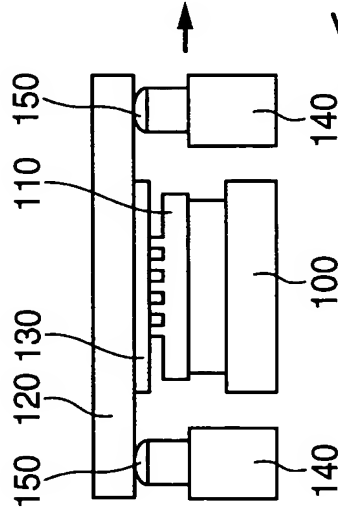


FIG.5C

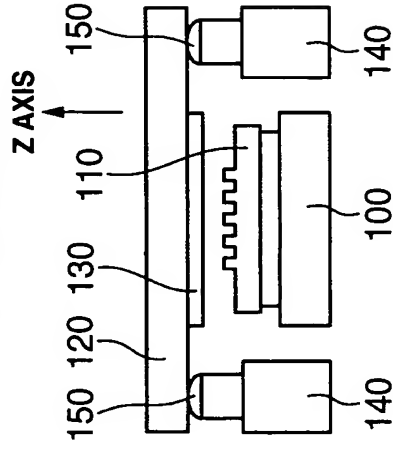


FIG.5D

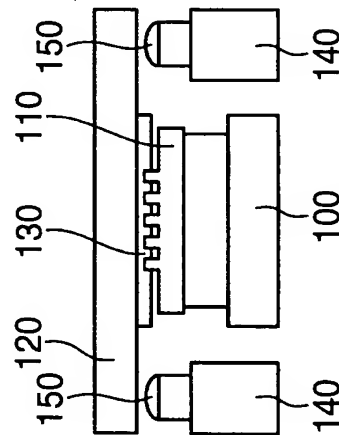


FIG.5E

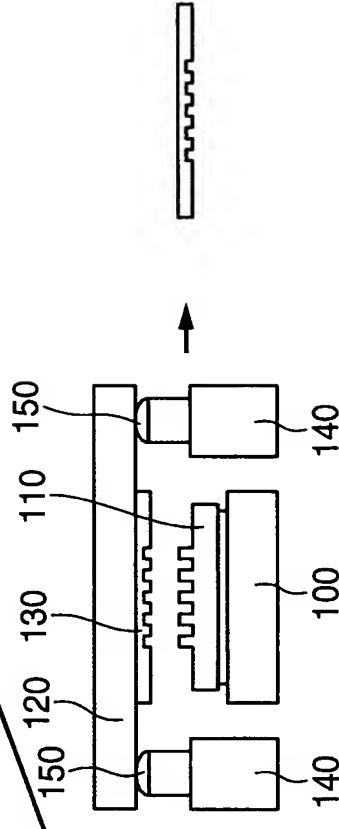
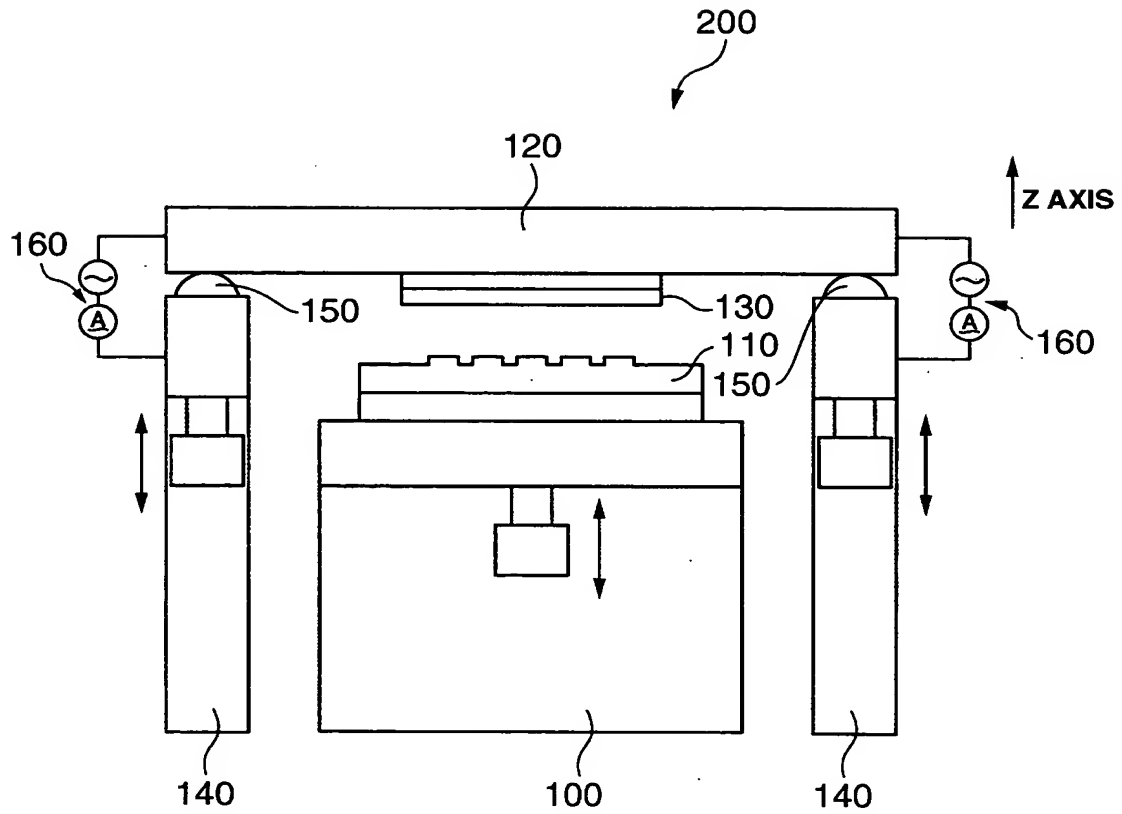


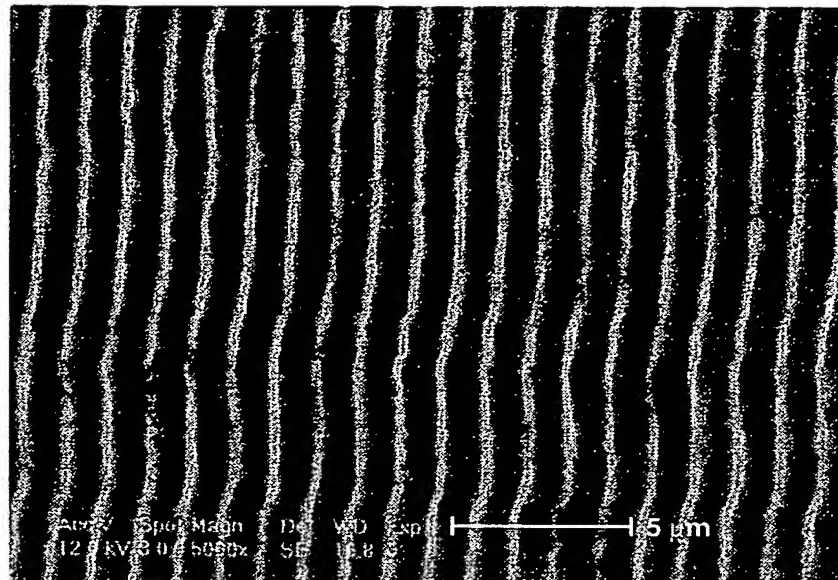
FIG.6



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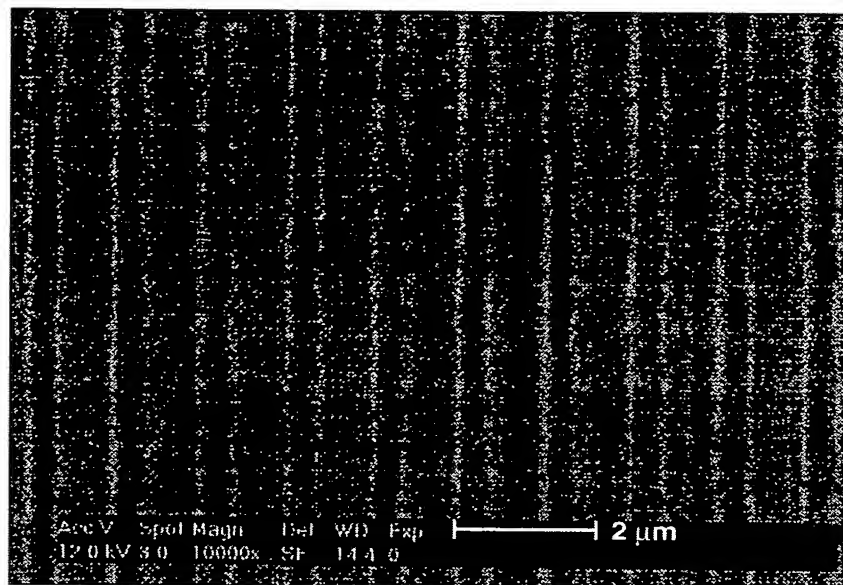
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FIG.7



MOLD TEMPERATURE: 130°C
FILM THICKNESS: 1 μm
SEM MAGNIFICATION FACTOR: 5000×

FIG.8



MOLD TEMPERATURE: 130°C
FILM THICKNESS: 200 nm
SEM MAGNIFICATION FACTOR: 10000×